DEVICE SMART CARD

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Term: 14 Years

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Field of Classification Search
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See application file for complete search history.

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CLAIM
We claim the ornamental design for a device smart card, as shown and described.

DESCRIPTION
FIG. 1 is a front view of a device smart card. The device smart card of the present claimed design is of negligible thickness. The space contained within the enclosed solid lines of the smart card of FIG. 1 represent perforations. The dot-dash boundary line encircling the inner sector of the card represents the boundary between the extent of the unclaimed surface area and the claimed surface area. Broken lines and space contained within the broken lines are not claimed.

1 Claim, 1 Drawing Sheet
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